

Filename: PMP7165REVB_BILLOFMATERIALS_bom.xls						
Date: 06/18/2012						
PMP7165REVB_BILLOFMATERIALS BOM						
COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C3	100uF	Capacitor, Electrolytic, SMD, 63Vdc	0.457 x 0.406	EEEVFK1J101P	Panasonic
1	C10	47nF	Capacitor, Ceramic, 50V, X7R, 15%	0603	Std	Std
1	C11	1nF	Capacitor, Ceramic, 100V, X7R	0805	Std	Std
1	C15	390pF	Capacitor, Ceramic, 50V, X7R, 15%	0603	Std	Std
1	C16	100nF	Capacitor, Ceramic, 50V, X7R, 15%	0603	Std	Std
1	C17	1uF	Capacitor, 16V, X7R, 15%	0603	Std	Std
1	C19	1uF	Capacitor, Ceramic, 100V, X7R, 15%	1206	Std	Std
1	C20	4.7uF	Capacitor, Ceramic, 16V, X5R, 15%	0805	Std	Std
1	C22	15nF	Capacitor, Ceramic, 50V, X7R, 15%	0603	Std	Std
8	C1-2 C4-6 C102-104	4.7uF	Capacitor, Ceramic, 50V, X7R, 15%	1210	Std	Std
2	C14 C9	22uF	Capacitor, Ceramic, 25V, X7R, 15%	1210	Std	Std
3	C18 C12 C200	1nF	Capacitor, Ceramic, 50V, X7R, 15%	0603	Std	Std
3	C7 C100-101	100nF	Capacitor, Ceramic, 25V, X7R, 15%	0603	Std	Std
2	C8 C13	560uF	Capacitor, Electrolytic, SMD, 10Vdc, 13mOhm	0.457 x 0.406	10SVPE560M	Sanyo OS-Con
1	D2	B560	Diode, Schottky, 5A, 60V	SMC	B560C	Diodes Inc
1	J4	PTC36SAAN	Header, Male 3-pin, 100mil spacing, (36-pin strip)	0.100 inch x 3	PTC36SAAN	Sullins
2	J1-2	PTC36SAAN	Header, Male 2-pin, 100mil spacing, (36-pin strip)	0.100 inch x 2	PTC36SAAN	Sullins
2	J3 J6	D120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	D120/2DS	OST
1	L1	10uH	Inductor, SMT, 28Asat, 2.86milliohm	1.100 x 1.100 inch	SER2918H-103KL	Coilcraft
1	L100	2.2uH	Inductor, 3Adc, 35mOhm, ±20%	0.240 x 0.268 inch	MOS6020-222ML	Coilcraft
2	Q1-2	CSD18537Q5A	MOSFET, Nch, 60V, 12.8 milliohm	TDSON-8	CSD18537Q5A	TI
2	Q3-4	CSD18531Q5A	MOSFET, Nch, 60V, 3.4 milliohm	TDSON-8	CSD18531Q5A	TI
1	R1	100k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R2	1Meg	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R3	1Meg	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R4	1	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R6	0	Resistor, Chip, 1/10W, 1%	0805	Std	Vishay
1	R7	0.56	Resistor, Metal Film, 1/4 watt, ± 5%	1206	Std	Std
1	R9	3.92K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R10	100K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R11	5.49K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R12	25.5K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R14	1.33K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R17	475	Resistor, Chip, 1/16W, 1%	0603	Std	Std

1	R18	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
3	R15-16 R100	10K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R5 R8	0	Resistor, Chip, 1/16W, 1%	0603	Std	Std
5	TP1 TP3-4 TP6 TP9	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
4	TP2 TP5 TP7-8	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	U1	TPS40170RGY	IC, 4.5V - 60V Wide Input Sync. PWM Buck Ctrl	QFN-20	TPS40170RGY	TI
Notes:	1. These assemblies are ESD sensitive, ESD precautions shall be observed.					
	2. These assemblies must be clean and free from flux and all contaminants.					
	Use of no clean flux is not acceptable.					
	3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.					
	4. Ref designators marked with an asterisk (**) cannot be substituted.					
	All other components can be substituted with equivalent MFG's components.					

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